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SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C220FB8NNNC
- Description : CAP, 22pF, 50V, ±1%, C0G, 0603

A. Samsung Part Number

		<u>CL</u>	<u>10</u>	<u>C</u>	<u>220</u>	E	<u>B</u>	<u>8</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>C</u>	
		1	2	3	4	5	6	1	8	9	10	1	
1 Series	Samsung	Multi-la	ayer C	eram	ic Cap	acito	r						
 Size 	0603 ((inch co	ode)		L:	1.6	± 0.1		mm		W:	0.8 ± 0.1	mm
③ Dielectric	C0G					(8)	Inne	r olo	otroc			Ni	
④ Delectric④ Capacitance	22 g	_e F				0	Term			le		Cu	
⑤ Capacitance	±1 9						Plati		lon			Sn 100%	(Pb Free)
tolerance						9	Prod	luct				Normal	· · ·
6 Rated Voltage	50 \	V				10	Spec	ial				Reserved for	⁻ future use
⑦ Thickness	0.8 ±	± 0.1	mm			1	Pack	agir	ng			Cardboard T	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1M±10% 0.5~5Vrms					
Q	840 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characterisitcs	(From -55 $^\circ\!$						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5°C, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or ± 0.25 _p F whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 173.33 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 330 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling within ±2.5% or ±0.25 _p F whichever is larger		Min. operating temperature \rightarrow 25 $^\circ$ C					
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.